

ICE LAKE COMe CPU Module

Bare-Metal Hardware

CPUC-ICX-0321-ZZ



The product is a basic form factor Computer-On-Module (COM) board that is designed to support a wide range of applications primarily in the commercial market segment. It is a Powerful Module in the COM roadmap and is therefore designed to be compatible with the existing System boards as well as FRS customer carrier boards designed to accept other Type 7 basic form factor COM Express module. The COM mezzanine form factor is the “COM Express” standard from PICMG

Key Features and Benefits

Processor Platform (ICE Lake)

COMe 3.0 spec update

2x DDR4 ECC SO-DIMM

BIOS recovery function Add

Additional I/O support

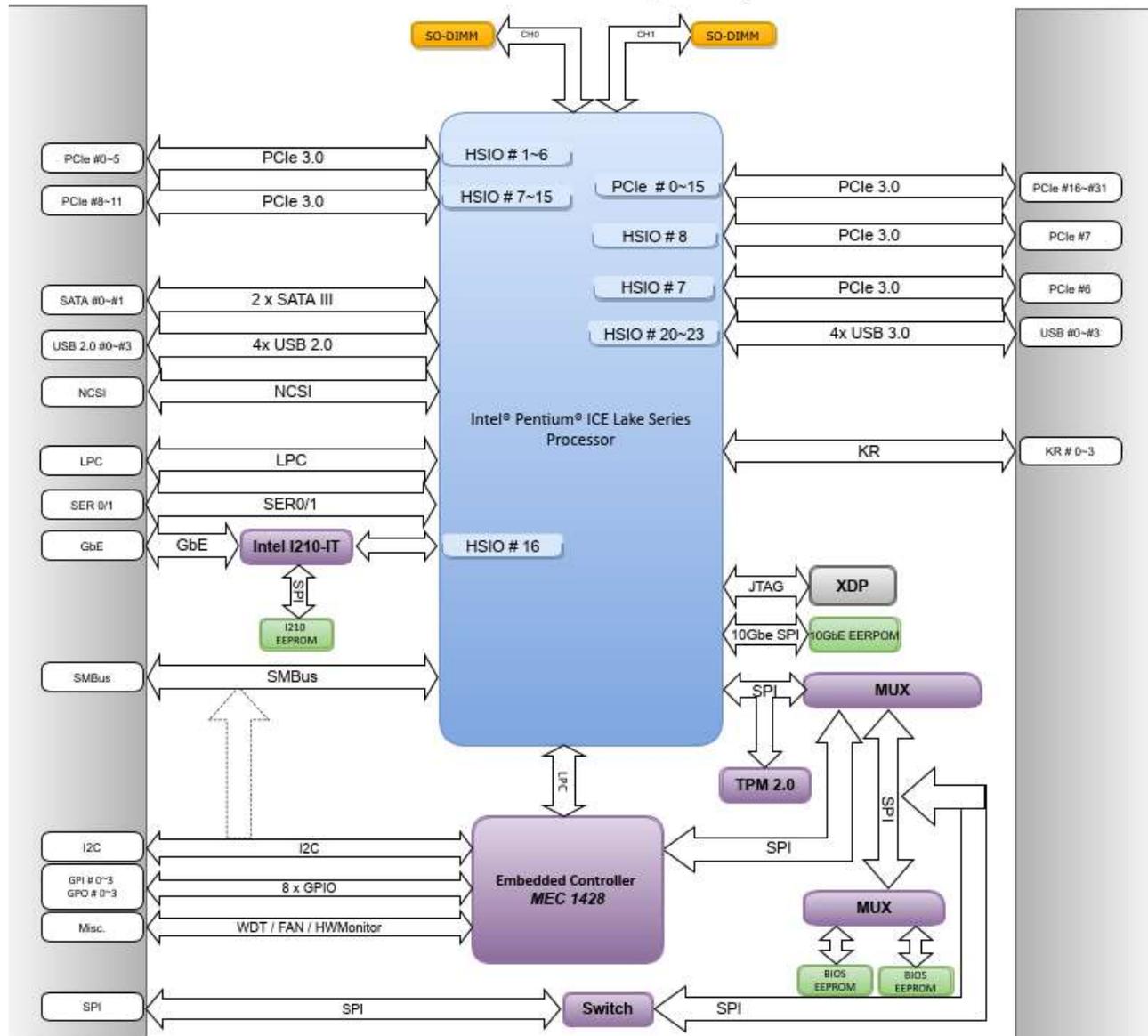
- Up to 32x PCIe lanes
- 1x GbE (MDI), 4x 10GbE (KR)
- USB 4x 2.0, 4x 3.0
- UEFI BIOS

The program consists of one logical module with several different SKUs, one heat spreader, or a passive heat sink. It re-uses the system board.

ICE Lake series

COM Express® Module 125 x 95 mm AT / ATX Mode -40°C ~ +85°C (Selected SKUs)

DDR4 ECC 2-Channel (base on SKU)



Form Factor	Type 7, Mid COM-Express® (125 x 95 mm)	
Processor	Intel® Pentium®	
	D1713NTe	D1734NT
Core	4	8
Freq.	3.3GHz	3.1GHz
Cache	10M	15M
Processor TDP	TBD	
BIOS	AMI BIOS	
In-Band ECC	Yes	
Memory	2 x DIMM up to 64GB	
SATA	2 x SATA III	
USB	4 x USB 3.1, 4 x USB 2.0	
Ethernet	1x GbE (MDI), 4x 10GbE (KR)	
Serial I/O	GPIO	8 x GPIO
	I2C	Baud Rate: 400KHz
	SMBus	Baud Rate: 100KHz
	UART	TBD
PCI Express	2 x PCIe 3.0 x 16	
Security	TPM 2.0, Intel®AES	

Dimension	125 x 95mm
Power DC IN	DC 12V/5V
Storage Temperature	-40°C to 85°C
Operation Temperature	0°C to 40°C(D1734NT) -40°C to 85°C(D1713NTe)
Certification	TBD
OS	TBD